

Final Product/Process Change Notification

Document #:FPCN23031XF Issue Date:27 Jan 2021

Title of Change:	Capacity Expansion of Assembly and Test operations of ON Semiconductor Cebu for SSOT6 package to ON Semiconductor Seremban, Malaysia.		
Proposed First Ship date:	4 May 2021 or earlier if approved by customer		
Contact Information:	Contact your local ON Semiconductor Sales Office or RamilAngelo.Nonato@onsemi.com.		
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Aileen.Allado@onsemi.com.		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .		
Marking of Parts/ Traceability of Change:	Affected parts from ON Semiconductor Seremban, Malaysia will be identified through product marking which follow ON Semiconductor marking format.		
Change Category:	Test Change, Assembly Change		
Change Sub-Category(s):	Shipping/Packaging/Marking, Material Change, Manufacturing Site Addition		
Sites Affected:			
ON Semiconductor Sites		External Foundry/Subcon Sites	
ON Semiconductor Seremban, Malaysia		None	

Description and Purpose:

This Product Change Notification is to announce that ON Semiconductor is expanding Assembly and Test Operations of Cebu former Fairchild Semiconductor for SSOT6 package to ON Seremban, Malaysia.

- No change on existing OPN. There will be two separate BOMs for ON Cebu, Philippines and ON Seremban, Malaysia. ON Seremban.
- Marking date code & Tape/Reel & Label follow with ON Semiconductor standard format.
- Case Outline is compatible with existing SSOT6 solder footprint.
- These products will continue being Pb-free, Halide free and RoHS compliant. Qualification tests are designed to show that the reliability of the impacted devices will continue to meet or exceed ON Semiconductor standards.

	Before Change Description	After Change Description		
Assembly & Test Site	ON Cebu, Philippines	ON Cebu, Philippines	ON Seremban, Malaysia	
Die Attach	Eutectic DA	Eutectic DA	Eutectic DA	
Mold Compound	CK5000A	CK5000A	G600FB	
Case Outline	419BL	Refer below		
Product marking change	Ex-FCS Format	ON Semiconductor format		

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Case Outline Before and After Change Description:

Dim	Before			Dim (mm)	After		
(mm)	Min	Nom	Max		Min	Nom	Max
Α	0.90	1.00	1.10	Α	0.90	1.00	1.10
A1	0.00	0.05	0.10	A1	0.00	0.05	0.10
A2	0.70	0.85	1.00	A2	0.70	0.85	1.00
А3	0.25 BSC		А3	0.25 BSC			
b	0.30	0.40	0.50	b	0.25	0.38	0.50
С	0.08	0.14	0.20	С	0.10	0.18	0.26
D	2.80	2.90	3.00	D	2.80	2.95	3.10
d	0.30 REF		d	0.30 REF			
Е	2.60	2.80	3.00	Е	2.50	2.75	3.00
E1	1.50	1.60	1.70	E1	1.30	1.50	1.70
е	0.95 BSC		е	0.95 BSC			
e1	1.90 BSC		e1	1.90 BSC			
L1	0.60 REF		L1	0.60 REF			
L2	0.35	0.45	0.55	L2	0.20	0.40	0.60
Ð	0°		8°	Ð	0°		10°

Reliability Data Summary:

QV DEVICE NAME: NDC7002N

RMS: F58116 PACKAGE: TSOT-23-6

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1008 hrs	0/77
HTGB	JESD22-A108	Ta= 150°C, 100% max rated Vgss	1008 hrs	0/77
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/77
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/77
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/77
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/77
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/77
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/308
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30

Electrical Characteristics Summary:

The temperature characterization and ESD performance meet datasheet specification. Detail of Electrical characterization result is available upon request.

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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Part Number	Qualification Vehicle
FDC6303N	NDC7002N
NDC7002N	NDC7002N
FDC6304P	NDC7002N
FDC6301N	NDC7002N
FDC6321C	NDC7002N

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